

General Description

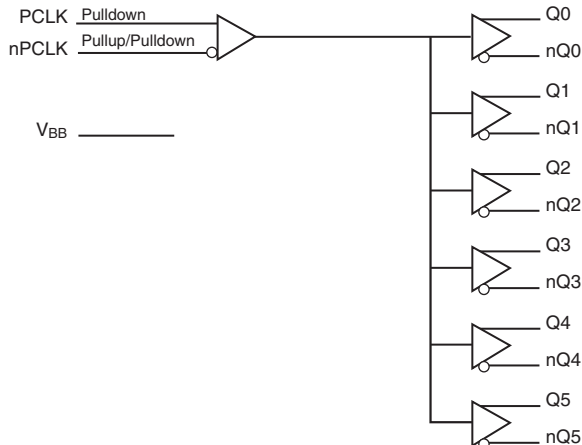


The ICS853S006I is a low skew, high performance 1-to-6 Differential-to-2.5V/3.3V LVPECL/ECL Fanout Buffer and a member of the HiPerClockS™ family of High Performance Clock Solutions from IDT. The ICS853S006I is characterized to operate from either a 2.5V or a 3.3V power supply. Guaranteed output and part-to-part skew characteristics make the ICS853S006I ideal for those clock distribution applications demanding well defined performance and repeatability.

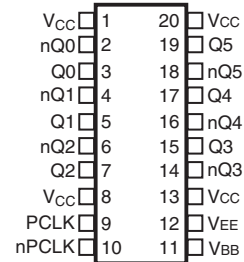
Features

- Six differential 2.5V, 3.3V LVPECL/ECL outputs
- One differential PCLK, nPCLK input pair
- PCLK, nPCLK pair can accept the following differential input levels: LVPECL, LVDS, CML, SSTL
- Maximum output frequency: >2GHz
- Output skew: 15ps (typical)
- Part-to-part skew: 30ps (typical)
- Propagation delay: 350ps (typical)
- LVPECL mode operating voltage supply range: $V_{CC} = 2.375V$ to $3.465V$, $V_{EE} = 0V$
- ECL mode operating voltage supply range: $V_{CC} = 0V$, $V_{EE} = -2.375V$ to $-3.465V$
- $-40^{\circ}C$ to $85^{\circ}C$ ambient operating temperature
- Available lead-free (RoHS 6) package

Block Diagram



Pin Assignment



ICS853S006I

20-Lead TSSOP

6.5mm x 4.4mm x 0.92mm package body

G Package

Top View

Table 1. Pin Descriptions

Number	Name	Type		Description
1, 8, 13, 20	V _{CC}	Power		Positive supply pin.
2, 3	nQ0, Q0	Output		Differential output pair. LVPECL interface levels.
4, 5	nQ1, Q1	Output		Differential output pair. LVPECL interface levels.
6, 7	nQ2, Q2	Output		Differential output pair. LVPECL interface levels.
9	PCLK	Input	Pulldown	Non-inverting differential LVPECL clock input.
10	nPCLK	Input	Pullup/ Pulldown	Inverting differential LVPECL clock input. V _{CC} /2 default when left floating.
11	V _{BB}	Output		Bias voltage.
12	V _{EE}	Power		Negative supply pin.
14, 15	nQ3, Q3	Output		Differential output pair. LVPECL interface levels.
16, 17	nQ4, Q4	Output		Differential output pair. LVPECL interface levels.
18, 19	nQ5, Q5	Output		Differential output pair. LVPECL interface levels.

NOTE: *Pullup and Pulldown* refer to internal input resistors. See Table 2, *Pin Characteristics*, for typical values.

Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
R _{PULLDOWN}	Input Pulldown Resistor			75		k Ω
R _{VCC/2}	Pullup/Pulldown Resistors			50		k Ω

Function Tables

Table 3. Clock Input Function Table

Inputs		Outputs		Input to Output Mode	Polarity
PCLK	nPCLK	Q0:Q5	nQ0:nQ5		
0	1	LOW	HIGH	Differential to Differential	Non-Inverting
1	0	HIGH	LOW	Differential to Differential	Non-Inverting
0	Biased; NOTE 1	LOW	HIGH	Single-Ended to Differential	Non-Inverting
1	Biased; NOTE 1	HIGH	LOW	Single-Ended to Differential	Non-Inverting
Biased; NOTE 1	0	HIGH	LOW	Single-Ended to Differential	Inverting
Biased; NOTE 1	1	LOW	HIGH	Single-Ended to Differential	Inverting

Note 1: Please refer to the Applications Information, "Wiring the Differential Input to Accept Single Ended Levels".

Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Supply Voltage, V_{CC}	4.6V (LVPECL mode, $V_{EE} = 0V$)
Negative Supply Voltage, V_{EE}	-4.6V (ECL mode, $V_{CC} = 0V$)
Inputs, V_I (LVPECL mode)	-0.5V to $V_{CC} + 0.5V$
Inputs, V_I (ECL mode)	0.5V to $V_{EE} - 0.5V$
Outputs, I_O Continuos Current Surge Current	50mA 100mA
V_{BB} Sink/Source, I_{BB}	$\pm 0.5mA$
Operating Temperature Range, T_A	-40°C to +85°C
Package Thermal Impedance, θ_{JA}	92.1°C/W (0 mps)
Storage Temperature, T_{STG}	-65°C to 150°C

DC Electrical Characteristics

Table 4A. Power Supply DC Characteristics, $V_{CC} = 2.375V$ to $3.465V$; $V_{EE} = 0V$, $T_A = -40^\circ C$ to $85^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{CC}	Positive Supply Voltage		2.375	3.3	3.465	V
I_{EE}	Power Supply Current			50		mA

Table 4B. LVPECL DC Characteristics, $V_{CC} = 3.3V$; $V_{EE} = 0V$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

Symbol	Parameter		-40°C			25°C			85°C			Units
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{OH}	Output High Voltage; NOTE 1		2.175	2.275	2.38	2.225	2.295	2.37	2.295	2.33	2.365	V
V_{OL}	Output Low Voltage; NOTE 1		1.405	1.545	1.68	1.425	1.52	1.615	1.44	1.535	1.63	V
V_{IH}	Input High Voltage (Single-ended)		2.075		2.36	2.075		2.36	2.075		2.36	V
V_{IL}	Input Low Voltage (Single-ended)		1.43		1.765	1.43		1.765	1.43		1.765	V
V_{BB}	Output Voltage Reference; NOTE 2		1.86		1.98	1.86		1.98	1.86		1.98	V
V_{PP}	Peak-to-Peak Input Voltage		150	800	1200	150	800	1200	150	800	1200	mV
V_{CMR}	Input High Voltage Common Mode Range; NOTE 3, 4		1.2		V_{CC}	1.2		V_{CC}	1.2		V_{CC}	V
I_{IH}	Input High Current	PCLK, nPCLK			200			200			200	μA
I_{IL}	Input Low Current	PCLK	-10			-10			-10			μA
		nPCLK	-200			-200			-200			μA

NOTE: Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.925V to -0.5V.NOTE 1: Outputs terminated with 50Ω to $V_{CCO} - 2V$.NOTE 2: Single-ended input operation is limited. $V_{CC} \geq 3V$ in LVPECL mode.NOTE 3: Common mode voltage is defined as V_{IH} .NOTE 4: For single-ended applications, the maximum input voltage for PCLK, nPCLK is $V_{CC} + 0.3V$ **Table 4C. LVPECL DC Characteristics, $V_{CC} = 2.5V$; $V_{EE} = 0V$, $T_A = -40^{\circ}C$ to $85^{\circ}C$**

Symbol	Parameter		-40°C			25°C			85°C			Units
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{OH}	Output High Voltage; NOTE 1		1.375	1.475	1.58	1.425	1.495	1.57	1.495	1.53	1.565	V
V_{OL}	Output Low Voltage; NOTE 1		0.605	0.745	0.88	0.625	0.72	0.815	0.64	0.735	0.83	V
V_{IH}	Input High Voltage (Single-ended)		1.275		1.56	1.275		1.56	1.275		1.56	V
V_{IL}	Input Low Voltage (Single-ended)		0.63		0.965	0.63		0.965	0.63		0.965	V
V_{PP}	Peak-to-Peak Input Voltage		150	800	1200	150	800	1200	150	800	1200	mV
V_{CMR}	Input High Voltage Common Mode Range; NOTE 2, 3		1.2		V_{CC}	1.2		V_{CC}	1.2		V_{CC}	V
I_{IH}	Input High Current	PCLK, nPCLK			200			200			200	μA
I_{IL}	Input Low Current	PCLK	-10			-10			-10			μA
		nPCLK	-200			-200			-200			μA

NOTE: Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.925V to -0.5V.NOTE 1: Outputs terminated with 50Ω to $V_{CCO} - 2V$.NOTE 2: Common mode voltage is defined as V_{IH} .NOTE 3: For single-ended applications, the maximum input voltage for PCLK, nPCLK is $V_{CC} + 0.3V$.

Table 4D. ECL DC Characteristics, $V_{CC} = 0V$; $V_{EE} = -3.465V$ to $-2.375V$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

Symbol	Parameter		-40°C			25°C			85°C			Units
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{OH}	Output High Voltage; NOTE 1		-1.125	-1.025	-0.92	-1.075	-1.005	-0.93	-1.005	-0.97	-0.935	V
V_{OL}	Output Low Voltage; NOTE 1		-1.895	-1.755	-1.62	-1.875	-1.78	-1.685	-1.86	-1.765	-1.67	V
V_{IH}	Input High Voltage (Single-ended)		-1.225		-0.94	-1.225		-0.94	-1.225		-0.94	V
V_{IL}	Input Low Voltage (Single-ended)		-1.87		-1.535	-1.87		-1.535	-1.87		-1.535	V
V_{BB}	Output Voltage Reference; NOTE 2		-1.44		-1.32	-1.44		-1.32	-1.44		-1.32	V
V_{PP}	Peak-to-Peak Input Voltage		150	800	1200	150	800	1200	150	800	1200	V
V_{CMR}	Input High Voltage Common Mode Range; NOTE 3, 4		$V_{EE}+1.2$		0	$V_{EE}+1.2$		0	$V_{EE}+1.2$		0	V
I_{IH}	Input High Current	PCLK, nPCLK			200			200			200	μA
I_{IL}	Input Low Current	PCLK	-10			-10			-10			μA
		nPCLK	-200			-200			-200			μA

NORE: Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.925V to -0.5V.

NOTE 1: Outputs terminated with 50Ω to $V_{CCO} - 2V$.

NOTE 2: Single-ended input operation is limited. $V_{CC} \geq 3V$ in LVPECL mode.

NOTE 3: Common mode voltage is defined as V_{IH} .

NOTE 4: For single-ended applications, the maximum input voltage for PCLK, nPCLK is $V_{CC} + 0.3V$

AC Electrical Characteristics

Table 5. AC Characteristics, $V_{CC} = 0$; $V_{EE} = -2.375V$ to $-3.465V$ or , $V_{CC} = 2.375V$ to $3.465V$; $V_{EE} = 0V$,
 $T_A = -40^{\circ}C$ to $85^{\circ}C$

Symbol	Parameter	-40°C			25°C			85°C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{MAX}	Output Frequency		>2			>2			>2		GHz
t_{PD}	Propagation Delay; NOTE 1		330			350			390		ps
$t_{sk(o)}$	Output Skew; NOTE 2, 4		15			15			17		ps
$t_{sk(pp)}$	Part-to-Part Skew; NOTE 3, 4		30			30			30		ps
f_{jit}	Buffer Additive Phase Jitter, RMS; 156.25MHz, Integration Range: 1kHz – 40MHz, refer to Additive Phase Jitter Section		0.08			0.09			0.10		ps
t_R / t_F	Output Rise/Fall Time		130			150			160		ps

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE: All parameters are measured at $f \leq 1GHz$, unless otherwise noted.

NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at the output differential cross points.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

Additive Phase Jitter

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the ***dBc Phase Noise***. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a

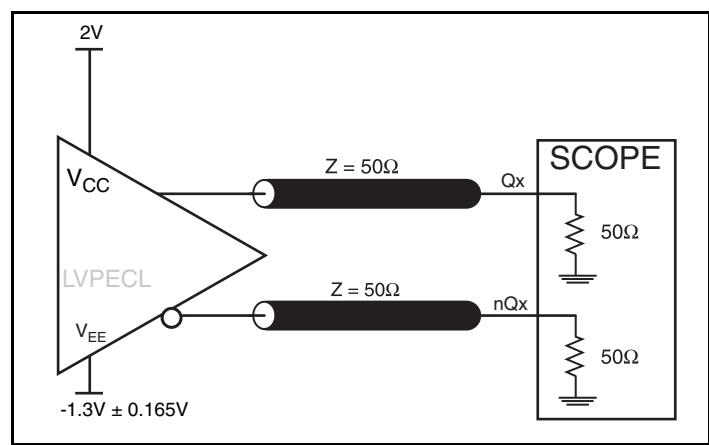
ratio of the power in the 1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a ***dBc*** value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.



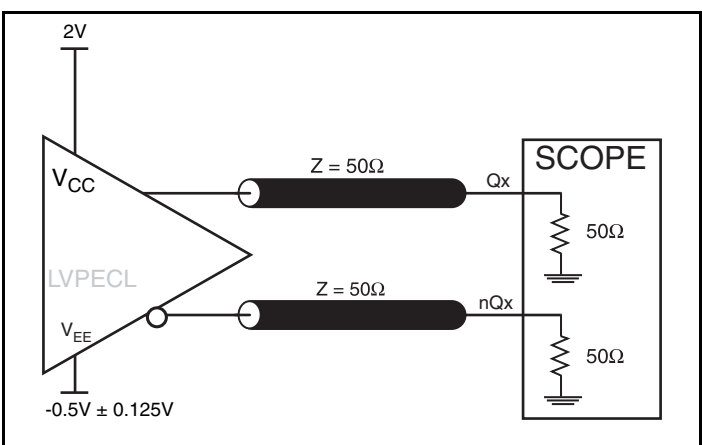
As with most timing specifications, phase noise measurements has issues relating to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the device. This

is illustrated above. The device meets the noise floor of what is shown, but can actually be lower. The phase noise is dependent on the input source and measurement equipment.

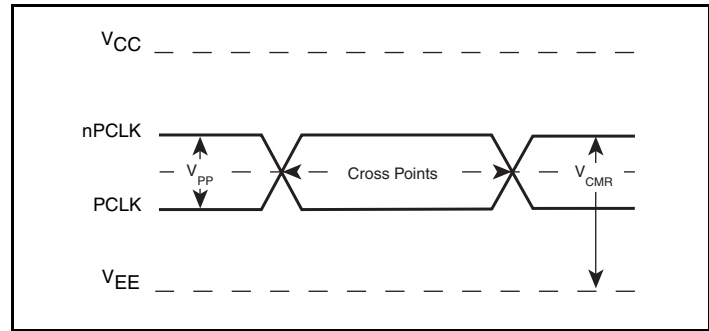
Parameter Measurement Information



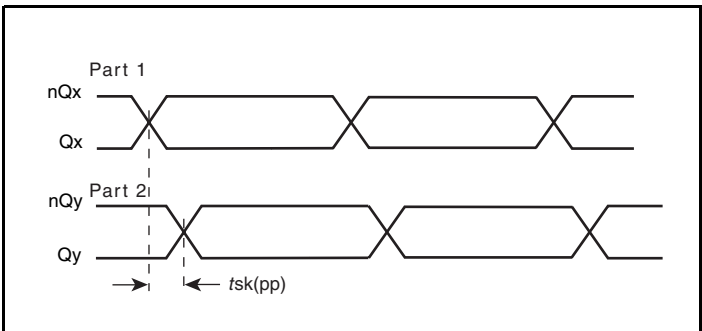
3.3V LVPECL Output Load AC Test Circuit



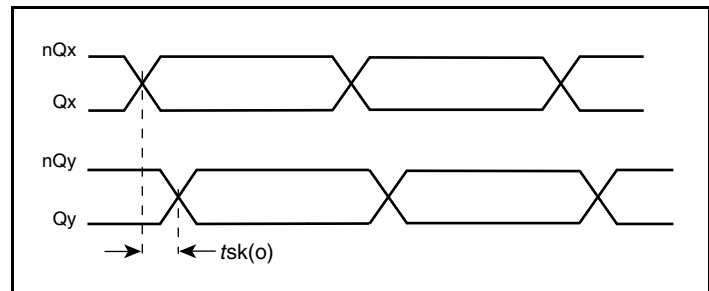
2.5V LVPECL Output Load AC Test Circuit



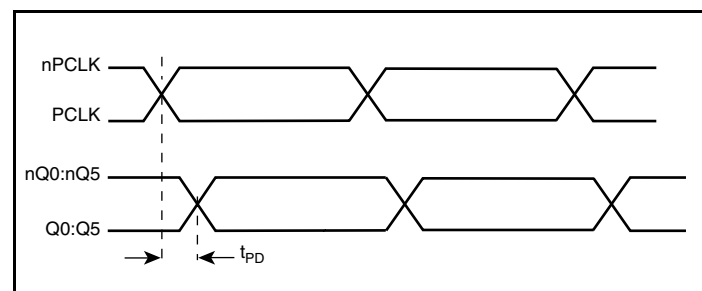
Differential Input Level



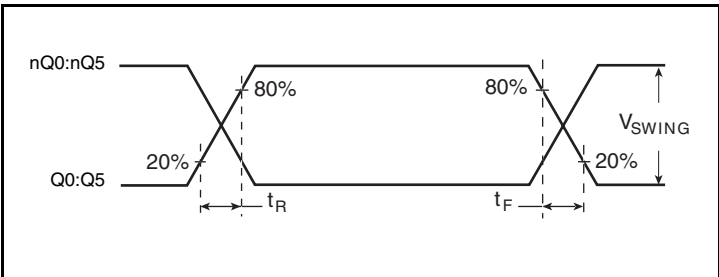
Part-to-Part Skew



Output Skew



Propagation Delay



Output Rise/Fall Time

Application Information

Wiring the Differential Input to Accept Single-ended LVCMOS Levels

Figure 1 shows an example of the differential input that can be wired to accept single-ended LVCMOS levels. The reference voltage level V_{BB} generated from the device is connected to the negative input.

The C1 capacitor should be located as close as possible to the input pin.

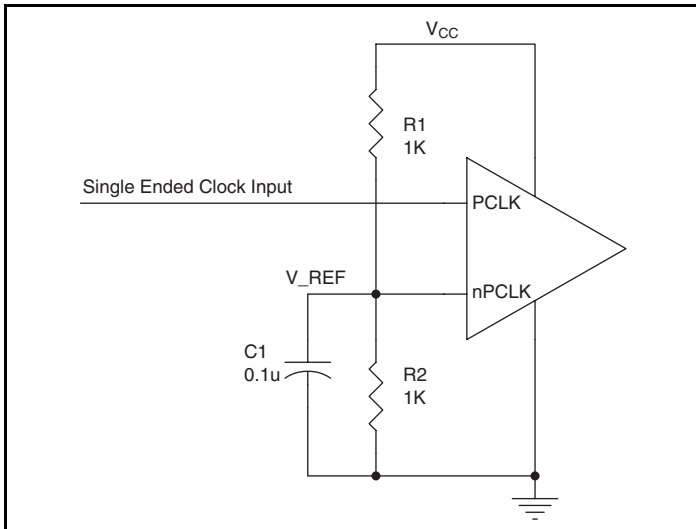


Figure 1A. Single-Ended LVCMOS Signal Driving Differential Input

Wiring the Differential Input to Accept Single-ended LVPECL Levels

Figure 2 shows an example of the differential input that can be wired to accept single-ended LVPECL levels. The reference voltage level V_{BB} generated from the device is connected to the negative input.

The C1 capacitor should be located as close as possible to the input pin.

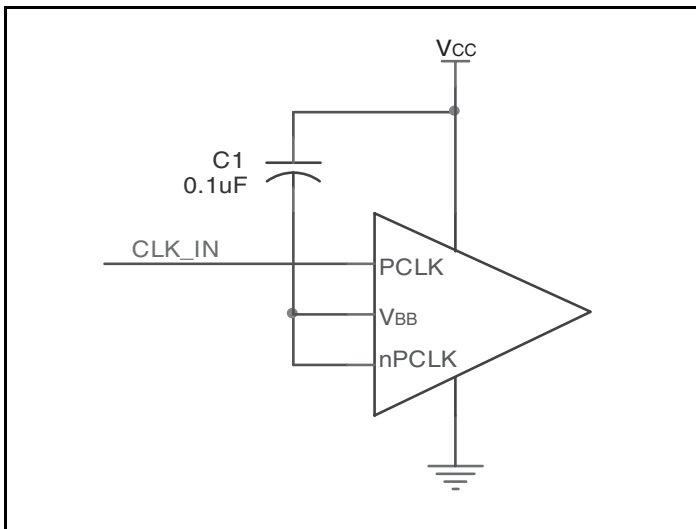


Figure 2. Single-Ended LVPECL Signal Driving Differential Input

LVPECL Clock Input Interface

The PCLK /nPCLK accepts LVPECL, LVDS, CML, SSTL and other differential signals. Both V_{SWING} and V_{OH} must meet the V_{PP} and V_{CMR} input requirements. *Figures 3A to 3F* show interface examples for the HiPerClockS PCLK/nPCLK input driven by the most common

driver types. The input interfaces suggested here are examples only. If the driver is from another vendor, use their termination recommendation. Please consult with the vendor of the driver component to confirm the driver termination requirements.

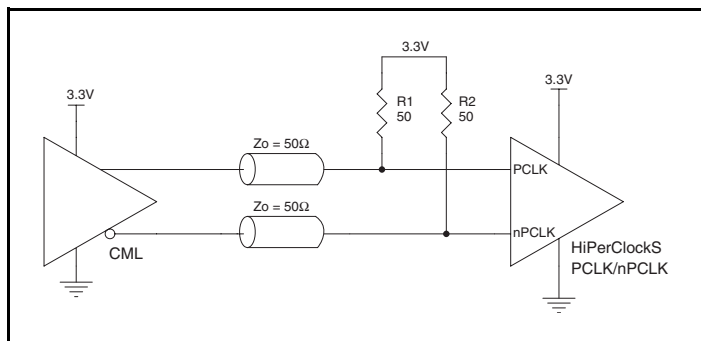


Figure 3A. HiPerClockS PCLK/nPCLK Input Driven by a CML Driver

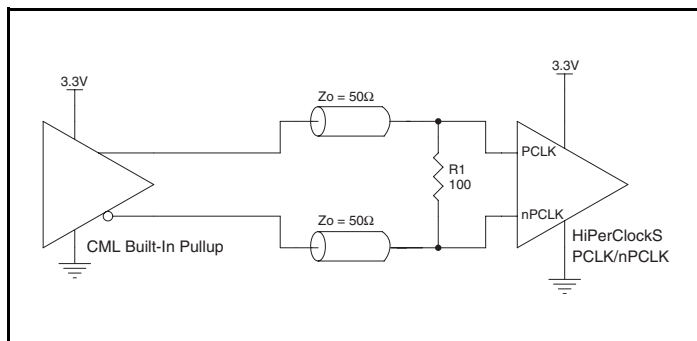


Figure 3B. HiPerClockS PCLK/nPCLK Input Driven by a Built-In Pullup CML Driver

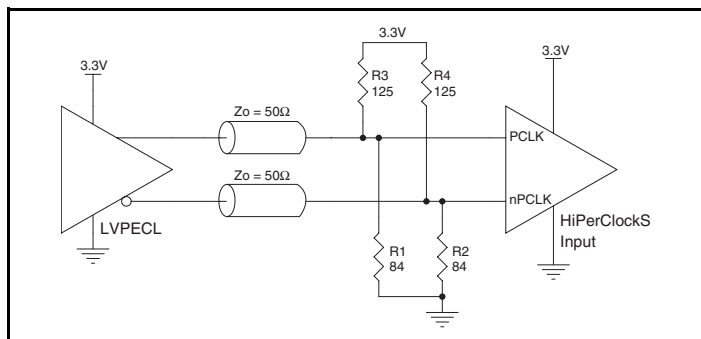


Figure 3C. HiPerClockS PCLK/nPCLK Input Driven by a 3.3V LVPECL Driver

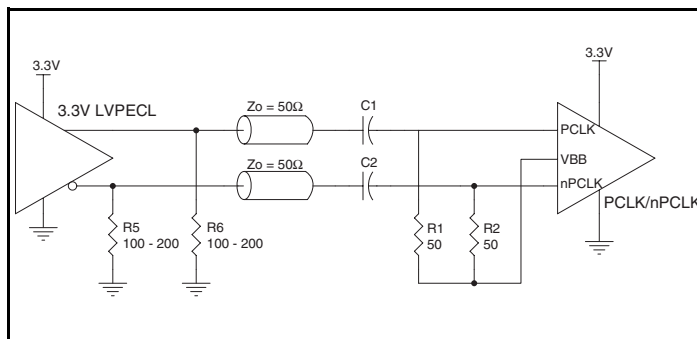


Figure 3D. HiPerClockS PCLK/nPCLK Input Driven by a 3.3V LVPECL Driver with AC Couple

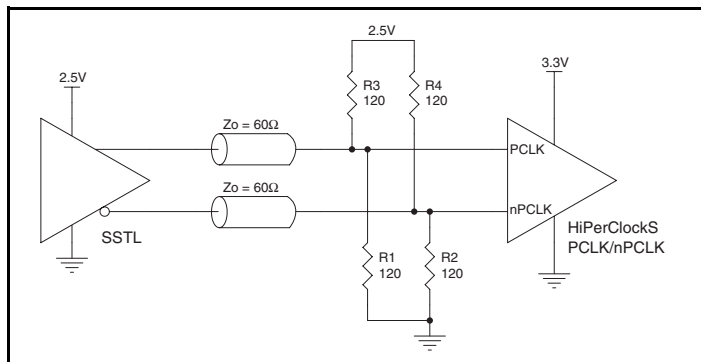


Figure 3E. HiPerClockS PCLK/nPCLK Input Driven by an SSTL Driver

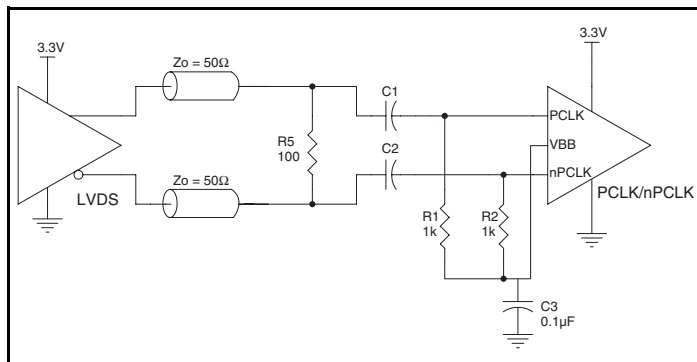


Figure 3F. HiPerClockS PCLK/nPCLK Input Driven by a 3.3V LVDS Driver

Recommendations for Unused Output Pins

Outputs:

LVPECL Outputs

All unused LVPECL outputs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.

Termination for 3.3V LVPECL Outputs

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

The differential outputs are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive 50Ω

transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion.

Figures 4A and 4B show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

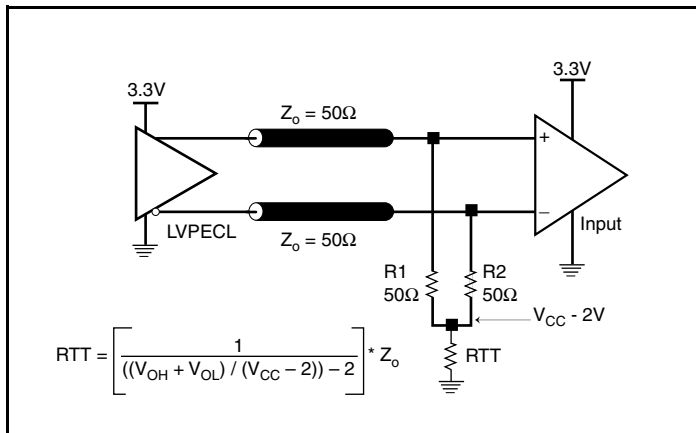


Figure 4A. 3.3V LVPECL Output Termination

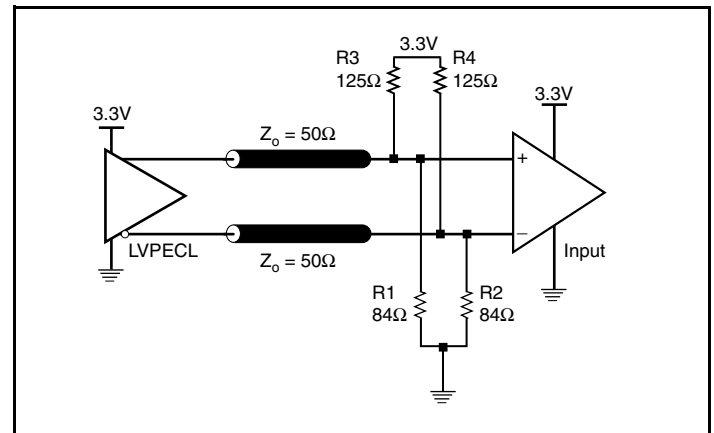


Figure 4B. 3.3V LVPECL Output Termination

Termination for 2.5V LVPECL Outputs

Figure 5A and Figure 5B show examples of termination for 2.5V LVPECL driver. These terminations are equivalent to terminating 50Ω to $V_{CC} - 2V$. For $V_{CC} = 2.5V$, the $V_{CC} - 2V$ is very close to ground

level. The R3 in Figure 5B can be eliminated and the termination is shown in Figure 5C.

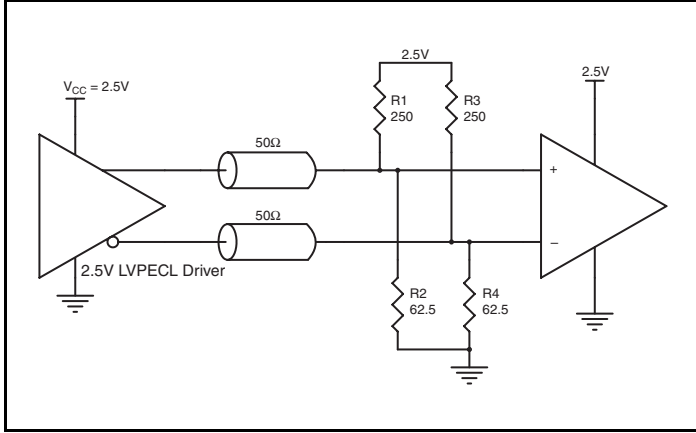


Figure 5A. 2.5V LVPECL Driver Termination Example

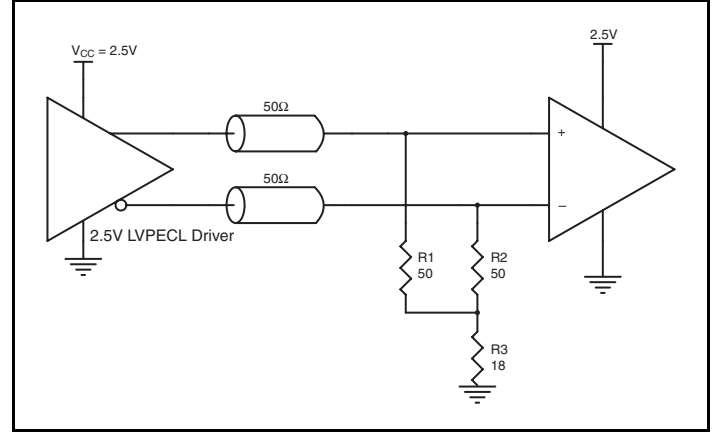


Figure 5B. 2.5V LVPECL Driver Termination Example

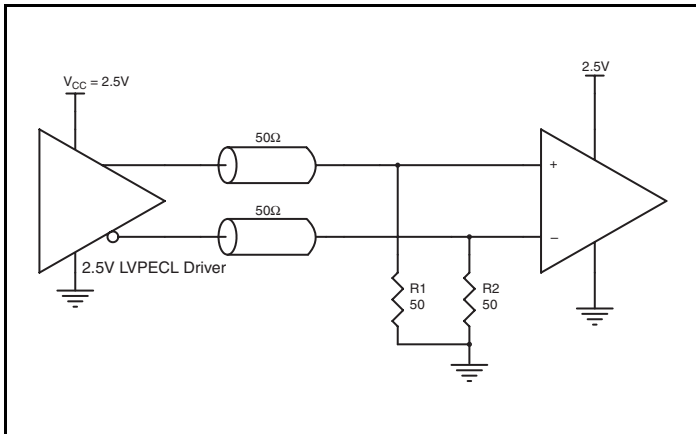


Figure 5C. 2.5V LVPECL Driver Termination Example

Schematic Example

Figure 6 shows a schematic example of ICS853S006I. The ICS853S006I input can accept various types of differential input signal. In this example, the inputs are driven by an LVPECL drivers. For the ICS853S006I LVPECL output driver, an example of LVPECL driver termination approach is shown in this schematic. Additional

LVPECL driver termination approaches are shown in the LVPECL Termination Application Note. It is recommended at least one decoupling capacitor per power pin. The decoupling capacitors should be physically located near the power pins. For ICS853S006I, the unused output can be left floating.

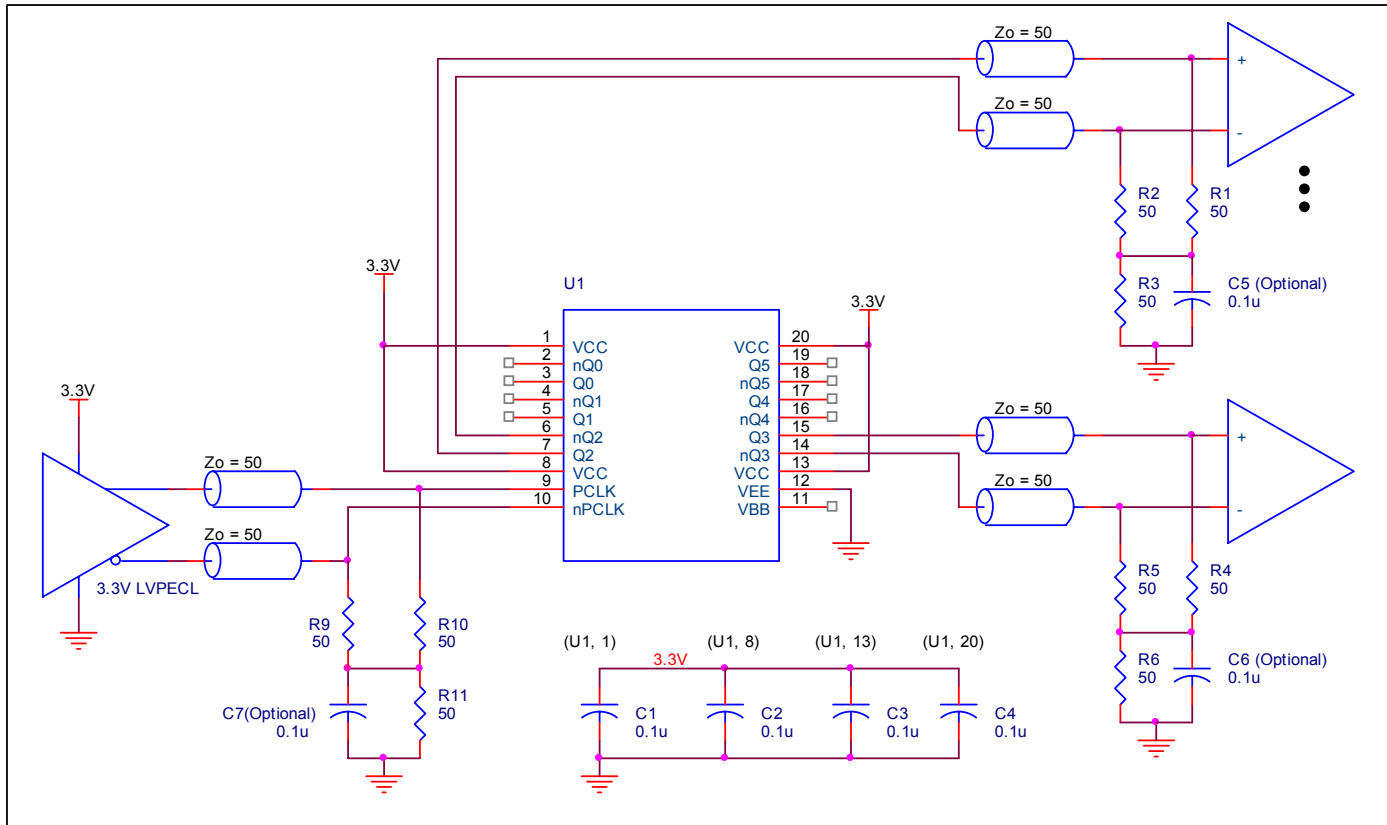


Figure 6. ICS853S006I Example LVPECL Clock Output Buffer Schematic

Power Considerations

This section provides information on power dissipation and junction temperature for the ICS853S006I. Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the ICS853S006I is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for $V_{CC} = 3.3V + 5\% = 3.465V$, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)_{MAX} = $V_{CC_MAX} * I_{EE_MAX} = 3.465V * 50mA = 173.25mW$
- Power (outputs)_{MAX} = **30.94mW/Loaded Output pair**
If all outputs are loaded, the total power is $6 * 30.92mW = 185.52mW$

Total Power_{MAX} (3.3V, with all outputs switching) = $173.25mW + 185.52mW = 358.77mW$

2. Junction Temperature.

Junction temperature, T_j , is the temperature at the junction of the bond wire and bond pad directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS devices is 125°C. Limiting the internal transistor junction temperature, T_j , to 125°C ensures that the bond wire and bond pad temperature remains below 125°C.

The equation for T_j is as follows: $T_j = \theta_{JA} * Pd_total + T_A$

T_j = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming no air flow and a multi-layer board, the appropriate value is 92.1°C/W per Table 6 below.

Therefore, T_j for an ambient temperature of 85°C with all outputs switching is:

$$85^\circ C + 0.359W * 92.1^\circ C/W = 118.1^\circ C. \text{ This is below the limit of } 125^\circ C.$$

This calculation is only an example. T_j will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (multi-layer).

Table 6. Thermal Resistance θ_{JA} for 20 Lead TSSOP, Forced Convection

θ_{JA} by Velocity			
Meters per Second	0	1	2.5
Multi-Layer PCB, JEDEC Standard Test Boards	92.1°C/W	86.5°C/W	83.0°C/W

3. Calculations and Equations.

The purpose of this section is to calculate the power dissipation for the LVPECL output pairs.

LVPECL output driver circuit and termination are shown in *Figure 7*.

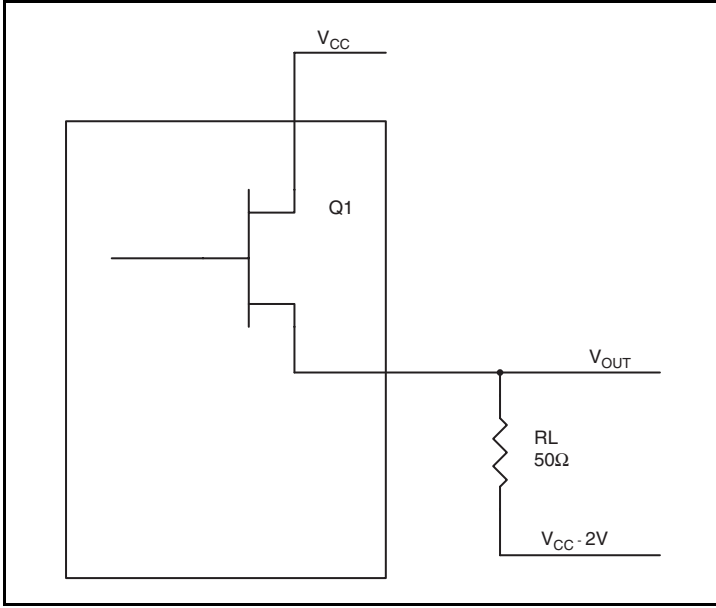


Figure 7. LVPECL Driver Circuit and Termination

To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of $V_{CC} - 2V$.

- For logic high, $V_{OUT} = V_{OH_MAX} = V_{CC_MAX} - 0.935V$
 $(V_{CC_MAX} - V_{OH_MAX}) = 0.935V$
- For logic low, $V_{OUT} = V_{OL_MAX} = V_{CC_MAX} - 1.67V$
 $(V_{CC_MAX} - V_{OL_MAX}) = 1.67V$

Pd_H is power dissipation when the output drives high.

Pd_L is the power dissipation when the output drives low.

$$Pd_H = [(V_{OH_MAX} - (V_{CC_MAX} - 2V))/R_L] * (V_{CC_MAX} - V_{OH_MAX}) = [(2V - (V_{CC_MAX} - V_{OH_MAX}))/R_L] * (V_{CC_MAX} - V_{OH_MAX}) = [(2V - 0.935V)/50\Omega] * 0.935V = \mathbf{19.92mW}$$

$$Pd_L = [(V_{OL_MAX} - (V_{CC_MAX} - 2V))/R_L] * (V_{CC_MAX} - V_{OL_MAX}) = [(2V - (V_{CC_MAX} - V_{OL_MAX}))/R_L] * (V_{CC_MAX} - V_{OL_MAX}) = [(2V - 1.67V)/50\Omega] * 1.67V = \mathbf{11.02mW}$$

$$\text{Total Power Dissipation per output pair} = Pd_H + Pd_L = \mathbf{30.94mW}$$

Reliability Information

Table 7. θ_{JA} vs. Air Flow Table for a 20 Lead TSSOP

θ_{JA} by Velocity			
Meters per Second	0	1	2.5
Multi-Layer PCB, JEDEC Standard Test Boards	92.1°C/W	86.5°C/W	83.0°C/W

Transistor Count

The transistor count for ICS853S006I is: 332

This device is pin and functional compatible with and is the suggested replacement for the ICS853006.

Package Outline and Package Dimensions

Package Outline - G Suffix for 20 Lead TSSOP

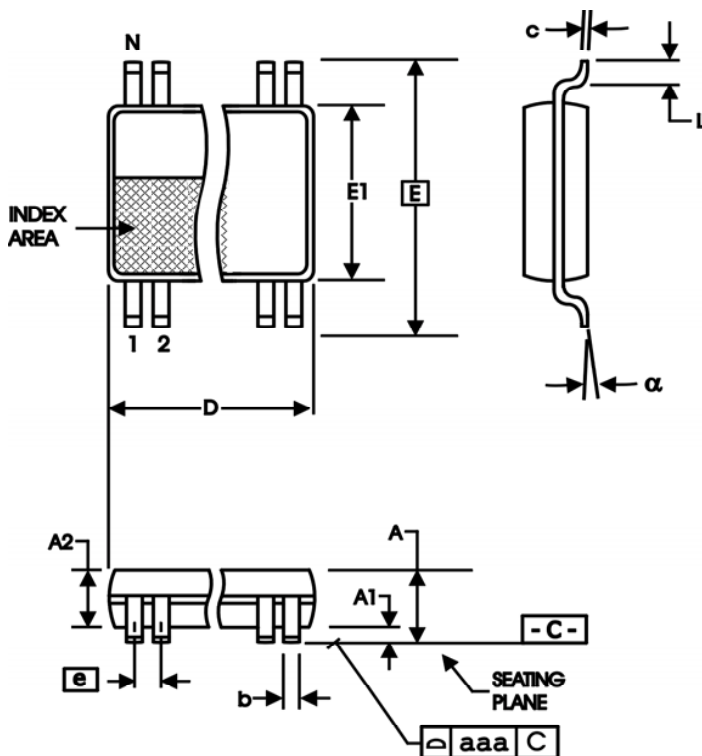


Table 8. Package Dimensions

All Dimensions in Millimeters		
Symbol	Minimum	Maximum
N	20	
A		1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	6.40	6.60
E	6.40 Basic	
E1	4.30	4.50
e	0.65 Basic	
L	0.45	0.75
α	0°	8°
aaa		0.10

Reference Document: JEDEC Publication 95, MO-153

Ordering Information

Table 9. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
853S006AGILF	ICS53S006AIL	20 Lead TSSOP	Tube	-40°C to 85°C
853S006AGILFT	ICS53S006AIL	20 Lead TSSOP	2500 Tape & Reel	-40°C to 85°C

NOTE: Parts that are ordered with an “LF” suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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